

AMENDMENTS TO THE ABSTRACT:

Please amend the Abstract originally appearing on page 26 of the application as follows:

ABSTRACT OF THE DISCLOSURE

A routing element for use with a multichip module. ~~The routing element~~ includes a substrate that carries conductive traces that provide either additional electrical paths or shorter electrical paths than those provided by a multichip module substrate. The conductive traces may be carried upon a single surface of the routing element substrate, be carried internally by the routing element substrate, or include externally and internally carried portions. The routing element also includes a contact pad positioned at each end of each conductive trace thereof to facilitate electrical connection of each conductive trace to a corresponding terminal of the substrate or to a corresponding bond pad of a semiconductor device of the multichip module. Multichip modules are also disclosed, as are methods for designing the routing element and methods in which the routing element is used.